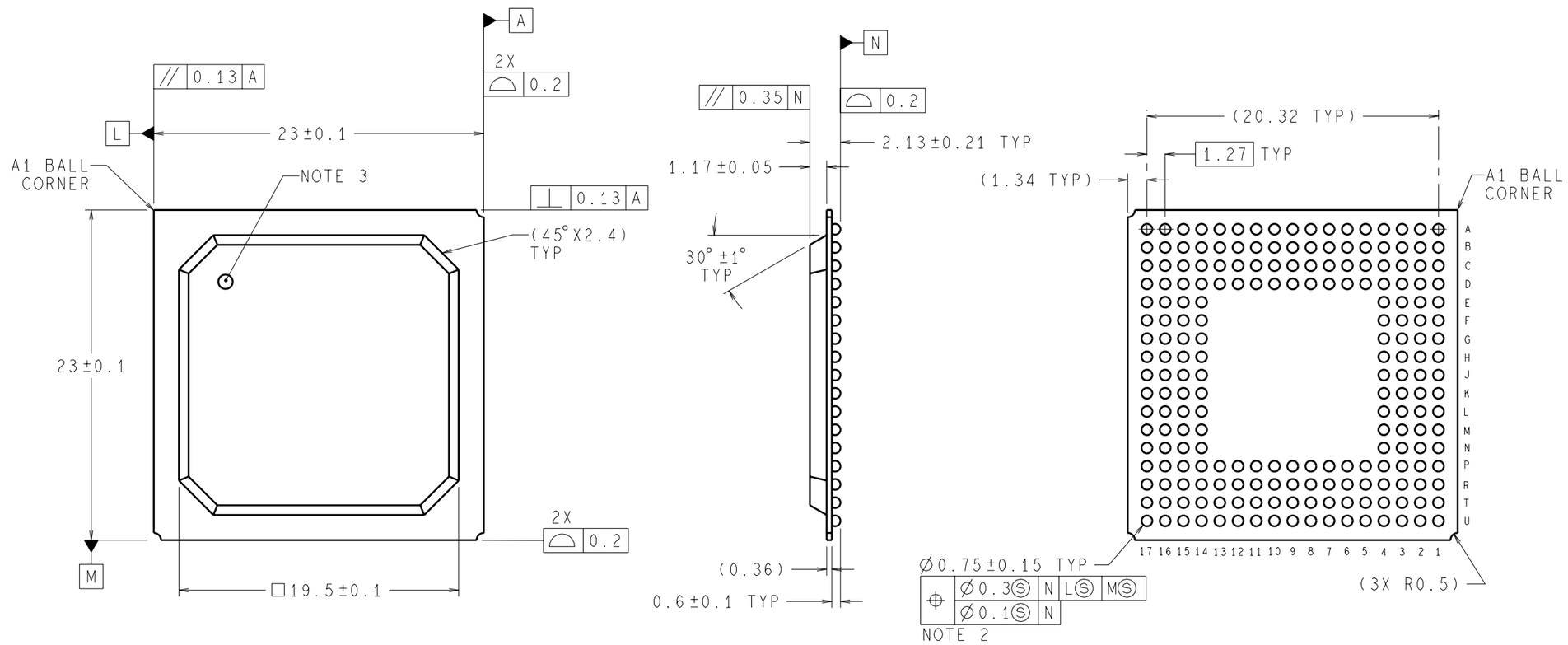
REVISIONS				
LTR	DESCRIPTION	E.C.N.	DATE	BY/APP'D
A	RELEASE TO DOCUMENT CONTROL	276	05/18/2001	MS/AP



DIMENSIONS ARE IN MILLIMETERS

NOTES: UNLESS OTHERWISE SPECIFIED

1. SOLDER BALL COMPOSITION: Sn 63%,Pb 37%.
2. DIMENSION IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM N.
3. THE MOLD SURFACE AREA MAY INCLUDE DIMPLE FOR A1 BALL CORNER IDENTIFICATION.
4. REFERENCE JEDEC REGISTRATION MO-151, VARIATION BAJ-2.

APPROVALS	DATE
DRAWN MARTA SUCHY	05/18/2001
DFTG. CHK. THANH LEQUANG	05/18/2001
ENGR. CHK. ANINDYA PODDAR	05/18/2001

PROJECTION INCH [MM]

National Semiconductor
2900 Semiconductor Dr, Santa Clara, CA 95052-8090

PBGA,
23 X 23 X 2.13mm,
208 BALL, 1.27mm PITCH

SCALE	SIZE	DRAWING NUMBER	REV
N/A	C	(SC)MKT-UDC208B	A

DO NOT SCALE DRAWING | SHEET 1 of 1